	Material Composition Declaration T GRATION CONNECTING GNICS INDUSTRIES* © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions. T				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lovel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
IPC Web Site for Information on http://www.ipc.org/IPC-175x			IPC-1752 Standard Form Type ³ Distribute			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				als and Mfg Information					
Supplier	r Information														
Company	name*		Company uni	que ID		1	Unique ID Aut	hority				Respons	e Date*		
nsemi												2024-04-	19		
Contact N	ame		Title - Contac	et]	Phone - Conta	ict*				Email -	Contact*		
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number	Mfr Item Number		iber Mfr Item Name			Effective Date Version Manufacturing Si		ring Site	Weight*		UOM	Unit Type		
		AR03300 A0-CP	CM1C21SHK	3 MP 1/3 CIS			2024-04-19			CP2		5	57.72	mg	Each
Ianufa	cturing Proccess Information	on													
	Terminal Plating / Grid Array Mate	erial To	erminal Base A	Alloy	J-STD-020 MSL	Rating	Peak Pro	cess Bod	ly Temperatu	re Max T	ime at Peak	Temperat	ure Num	nber of Reflow Cy	cles
	SnAgCu	С	U Alloy		5		260		С	30		secon	ds 3		
omments															
or more i	information regarding material co	omposition p	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.53	mg		Misc.	proprietary data		0.0362	mg
			Supplier	Silicon (Si)	7440-21-3		9.3994	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0943	mg
Die Attach	0.91	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.3413	mg
			Supplier	Ethylene Glycol	107-21-1		0.0091	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0273	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.1911	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.3413	mg
Electrode	0.97	mg	Supplier	Titanium (Ti)	7440-32-6		0.0006	mg
			В	Nickel (Ni)	7440-02-0		0.5775	mg
			Supplier	Gold (Au)	7440-57-5		0.0233	mg
			Supplier	Copper (Cu)	7440-50-8		0.0146	mg
			Supplier	Aluminum (Al)	7429-90-5		0.354	mg
Glass Lid /Cap	40.57	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		5.7609	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		20.285	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		9.7368	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		4.4627	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.0406	mg
			В	Arsenic Trioxide (As2O3)	1327-53-3		0.284	mg
Lid Attach	0.01	mg		Photoinitiator	proprietary data		0.0025	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0075	mg
Passivation	0.91	mg	Supplier	Pentaerythritol triacrylate	3524-68-3		0.1365	mg
			Supplier	2-(2-methoxypropoxy)propanol	34590-94-8		0.091	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.091	mg
			Supplier	9-Phenylacridine	602-56-2		0.0455	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.546	mg
older Ball	0.71	mg	Supplier	Silver (Ag)	7440-22-4		0.0543	mg
			Supplier	Tin (Sn)	7440-31-5		0.6397	mg
			Supplier	Copper (Cu)	7440-50-8		0.016	mg
bubstrate and Solder Mask	4.11	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.411	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		1.9523	mg

Supplier Bismaleimide Triazine resin Proprietary Data 1.7468 mg				Supplier	Bismaleimide Triazine resin	Proprietary Data		1.7468	mg
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